

ABSTRACT

A photosensitive transparent resin film, provided selectively with a groove reaching a transparent substrate is formed on the transparent substrate, and a wiring portion is provided in the groove substantially in flush with the photosensitive transparent resin film. The wiring portion can be formed quickly while controlling the thickness easily by preprocessing the surface of the photosensitive transparent resin film or the bottom face of the groove before the wiring portion is set in the groove.